Appl. No. 10/696,816 Reply to Office action of 11/02/2006

provide better connection during packaging to the top metal interconnect level 104. As

also noted by the Examiner, the "cap layer" as understood from the specification would

not describe the bump layer of List.

In light of the above, Applicant respectfully requests withdrawal of the objection

and continued allowance of claims 2 and 4-10. If the Examiner has any questions or

other correspondence regarding this application, Applicant requests that the Examiner

contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,

/Jacqueline J Garner/

Jacqueline J. Garner

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